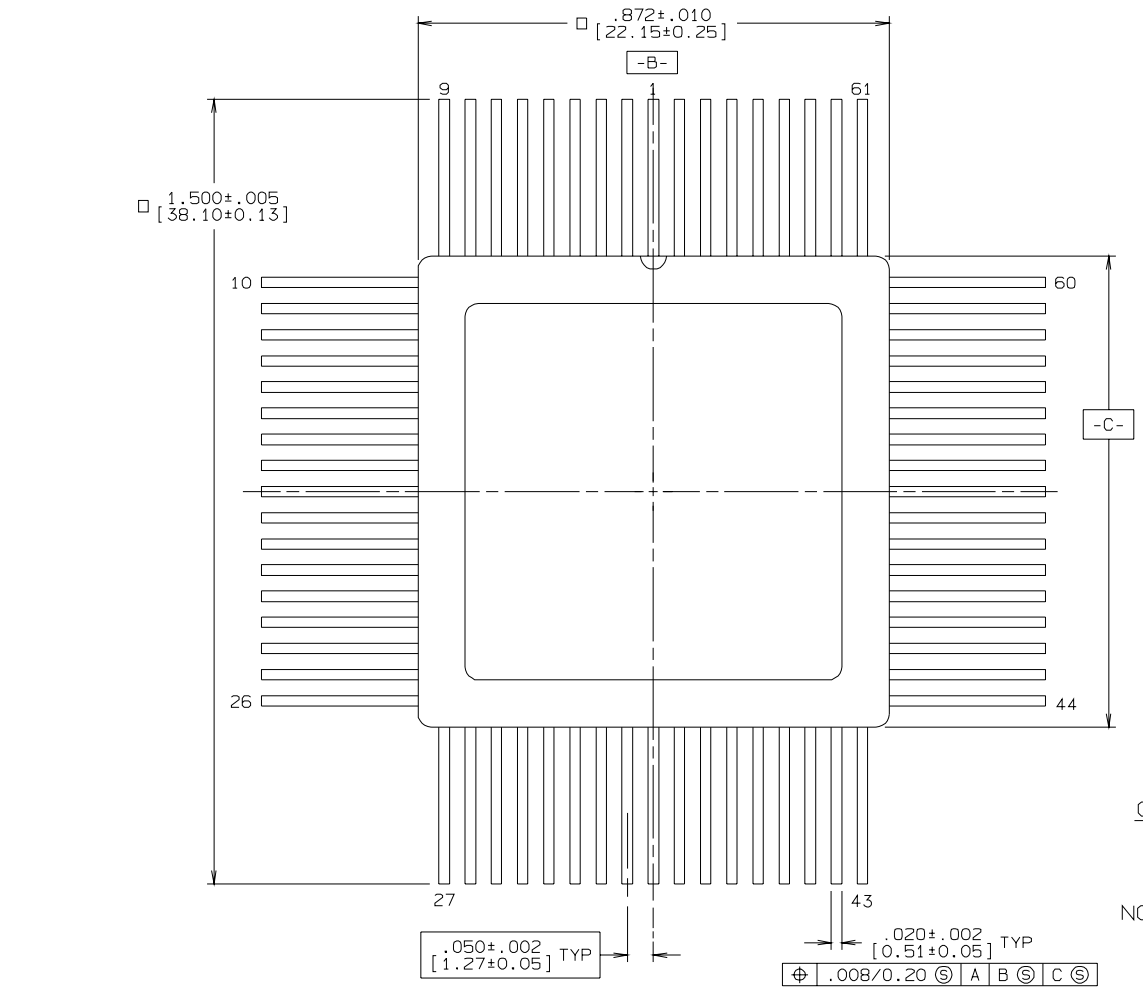
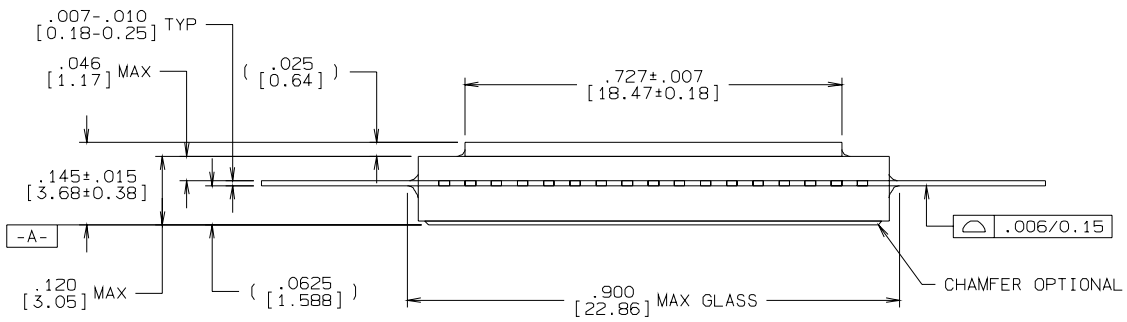
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
C	REDRAW TO SUN: ±.007 WAS ±.002	09557	03/04/93	DEG/SC
D	ADD DIM (.0625 [1.588]); NOTE 2: MIL-I-38535 WAS MIL-M-38510; UPDATE MIL/AERO STAMP; ADD "CONTROLLING DIMENSION: INCH"	10776	01/31/95	MS/



CONTROLLING DIMENSION: INCH

NOTES: UNLESS OTHERWISE SPECIFIED

1. MAXIMUM BURR AFTER LEAD TRIM .003 IN/0.08 mm.
2. LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO MIL-I-38535 TO A MINIMUM THICKNESS OF 200 MICROINCHES/5.08 MICROMETERS. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR TIN PLATE.
3. LEAD THICKNESS MAY BE INCREASED BY .003 IN/0.08 mm MAXIMUM AFTER LEAD FINISH IS APPLIED.



MIL-I-38535
CONFIGURATION CONTROL

APPROVALS	DATE
DRAWN D.E.GRADY	03/04/93
DFTG. CHK.	
ENGR. CHK.	

National Semiconductor
2900 Semiconductor dr, Santa Clara, CA 95052-8090

CERQUAD, 68 LEAD

PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
INCH [MM]	N/A	C	MKT-W68A	D

DO NOT SCALE DRAWING — SHEET 1 OF 1